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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: KOUBUCHI et al

Serial No.: 10/619,039

Filed: July 14, 2003

For: Semiconductor Integrated Circuit Device

Group: 2814

Examiner: L. Pham

INFORMATION DISCLOSURE  
STATEMENT UNDER 37 CFR 1.97 & 1.98

Mail Stop: DD  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

April 5, 2006

Sir:

In the matter of the above-identified application, applicants are submitting herewith a copy of a communication from a foreign patent office in a counterpart foreign application and copies of the documents listed in the attached form equivalent to Form PTO-1449, other than U.S. patent documents, for the Examiner's consideration.

This information disclosure statement is being submitted before the mailing date of either a final action or a notice of allowance and is accompanied by the fee of \$180.00 set forth in 37 CFR 1.17(p).

To the extent the documents listed on the attached form equivalent to Form PTO-1449 are not in the English language, the requirement of 37 CFR 1.98(a)(3) for a concise explanation of the relevance is satisfied by an English language version or

translation of the foreign patent office report citing the documents and the following comments from applicants.

The priority document of Japanese Patent Laid-open 09-55421 corresponds to Korean Patent Laid-open 1996-0043102. This document does not disclose dummy regions formed at the scribe area.

Korean Patent Laid-open 1994-0009350 has no foreign counterpart. This document does not disclose dummy regions formed at the scribe area.

Japanese Patent Laid-Open 55-135837 has no foreign counterpart. This document is directed to a method of forming a master mask 10 having chip name pattern 4 by using reticle 7, 8. This document does not disclose dummy regions or dummy interconnects formed at the scribe area in a semiconductor substrate.

The priority documents of Korean Patent Laid-open 1997-011056 and U.S. Patent No. 5,422,236 correspond to Japanese Patent Laid-open 06-125013. This document does not disclose dummy regions or dummy interconnects formed at the scribe area.

The priority documents of Korean Patent Laid-open 1997-011056, U.S. Patent No. 5,323,046 and U.S. Patent No. 5,441,916 correspond to Japanese Publication 2802455. This document does not disclose dummy regions or dummy interconnects formed at the scribe area.

As to U.S. Patent No. 4,916,087, this document is a member of the same patent family as 02-138757 and is directed to problem of a concave portion 7 in a narrow trench in forming SiO<sub>2</sub> by using dry etching, as shown in Fig. 5f. Moreover, this concave portion 7 occurs at the narrow trench formed between active region, as shown in Figure 2. In other words, there is no problem in the broad trench in this

document. In this document, first, the narrow trench is filled as shown in Fig. 1d, next, the broad trench is filled as shown in Fig. 1g.

As to U.S. Patent No. 5,361,234, this document is a member of the same patent family as 06-216332 and is directed to dummy word lines formed adjacent to word lines of memory array. This document does not disclose dummy interconnections formed at the scribe area.

As to Japanese Patent Laid-open 06-151768, this document is directed to auxiliary film 16, formed at the same layer as bit lines 5 of memory cell, formed between memory blocks 54. This document does not disclose dummy interconnections formed at the scribe area.

As to Japanese Utility-Model Laid-open 03-071630, this document is directed to the dummy A1 pattern 13 on the chip 11. This document does not disclose dummy interconnections formed at the scribe area.

As to U.S. Patent No. 4,916,514 and Japanese Patent Laid-open 05-267460, this document is directed to the dummy patterns formed between the wiring 3. This document does not disclose dummy patterns formed at the scribe area.

As to Japanese Patent Laid-open 06-069201, this document is directed to the insulating pattern 51 formed between the wiring 3.

As to Japanese Patent Laid-open 01-149435 and 03-38043, this document does not disclose any dummy patterns formed at the scribe area.

U.S. Patent No. 5,459,093 corresponding to Japanese Patent Laid-open 06-326106, WO96/15552, U.S. Patent No. 5,498,565 are already cited in the office action mailed November 15, 2005, in related application serial number 10/956,159.

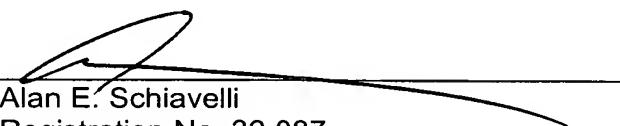
It is respectfully requested that this information disclosure statement be

considered by the Examiner.

Please charge any shortage in the fees due in connection with the filing of this paper, including extension of time fees, to the deposit account of Antonelli, Terry, Stout & Kraus Deposit Account No. 01-2135 (Case: 501.36127CC3), and please credit any excess fees to such deposit account.

Respectfully submitted,

ANTONELLI, TERRY, STOUT & KRAUS, LLP

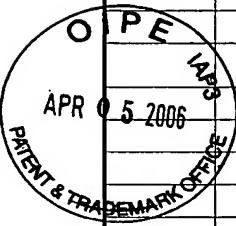


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Attachments

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Substitute for form 1449A/PTO		<b>Complete if Known</b>	
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>		Application Number	<b>10/619,039</b>
(use as many sheets as necessary)		Filing Date	<b>7/14/2003</b>
		First Named Inventor	<b>Yasushi KOBUCHI</b>
		Art Unit	<b>2814</b>
		Examiner Name	<b>Pham</b>
Sheet	<b>1</b>	of	<b>2</b>
		Attorney Docket Number	
		<b>1374.36127CC3</b>	



## **U.S. PATENT DOCUMENTS**

## **FOREIGN PATENT DOCUMENTS**

Examiner Initials'	Cite No. <sup>1</sup>	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T <sup>6</sup>
		Country Code <sup>3</sup> -Number <sup>4</sup> -Kind Code <sup>5</sup> (if known)				
		KR 1996-0043102	12-01-1998			
		JP 09-55421	02-25-1997	Kwon		
		KR 1994-0009350	10-07-1994			
		JP 55-135837	10-23-1980	Takao		
		KR 1997-011056	07-05-1997			
		JP 6-125013	05-06-1994	Yuji		
		KR 1996-0000962	05-15-1996			
		JP 2802455	07-17-1998	Kaoru		

Examiner Signature		Date Considered	
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. 1 Applicant's unique citation designation number (optional). 2 See Kinds Codes of USPTO Patent Documents at [www.uspto.gov](http://www.uspto.gov) or MPEP 901.04. 3 Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). 4 For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. 5 Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. 6 Applicant is to place a check mark here if English language Translation is attached.

This collection of information is required by 37 CFR 1.97 and 1.98. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 2 hours to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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 <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>				<b>Complete if Known</b>	
<p>Substitute for form 1449A/PTO</p> <p>(use as many sheets as necessary)</p>				Application Number	10/619,039
				Filing Date	7/13/2003
				First Named Inventor	Yasushi KOBUCHI
				Art Unit	2814
				Examiner Name	Pham, L.
Sheet	2	of	2	Attorney Docket Number	
1374-36127CC3					

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		Country Code <sup>3</sup> -Number <sup>4</sup> -Kind Code <sup>5</sup> (if known)				
		WO 90/03046	03-22-1990	Nowak		
		JP 05-267460	10-15-1993	Junichi		
		JP 06-069201	03-11-1994	Taiji		
		JP 01-149435	06-12-1989	Tetsuya		
		JP 06-151768	05-31-1994	Yoshiki		
		JP 03-071630-0	07-19-1991			
		JP 02-138757	05-28-1990	Hidehisa		
		JP 05-275527	10-22-1993	Tetsuo		
		WO 96/15552	05-23-1996	Moon		
		JP 06-326106	11-25-1994	Hideaki		
		JP 06-069201	03-11-1994	Taiji		
		JP 03-038043	02-19-1991	Nobuo		
		JP 06-216332	08-5-1994	Shinya		
		JP 06-151768	05-31-1994	Yoshiki		
		JP 2-504575	12-20-1990	Nowak		

<b>Examiner Signature</b>		<b>Date Considered</b>	
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